

1. Record Nr.	UNISA996499862603316
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Titolo	Advanced materials and components for 5G and beyond / / Colin Tong
Pubbl/distr/stampa	Cham, Switzerland : , : Springer, , [2022] ©2022
ISBN	9783031172076 9783031172069
Descrizione fisica	1 online resource (276 pages)
Collana	Springer Series in Materials Science ; ; v.327
Disciplina	405
Soggetti	Physics
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Nota di bibliografia	Includes bibliographical references and index.
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